

ABSTRACT OF THE DISCLOSURE

Wire bonding being performed by, following the formation of a neck portion on a wire at a first bonding point, raising the capillary from the neck portion while paying out a first specified length of wire, causing the capillary to move toward a second bonding point so that a first kink is formed on the wire, then lowering the capillary so that a second specified length of wire is taken into the capillary, and moving the capillary in the opposite direction from the second bonding point so as to form a second kink, and then raising the capillary, while paying out the wire, until the first kink is positioned at the lower end of the capillary, and finally, with the wire being held in this state, moving the capillary to the second bonding point, thus completing a wire loop between the first and second bonding points.